

4 CHANNEL LOW CAPACITANCE TVS DIODE ARRAY
Product Summary

V_{BR} (Min)	I_{PP} (Max)	C_T (Typ)
6V	5.5A	0.55pF

Description

The DT1240-04LP20 is a high-performance device suitable for protecting four high speed I/Os. These devices are assembled in DFN2010-8 packages and have high ESD surge capability and low capacitance.

Applications

Typically used at high-speed ports such as USB2.0, USB3.0, IEEE1394 (Firewire[®], iLink[™]), Serial ATA, DVI[™], HDMI, PCI.

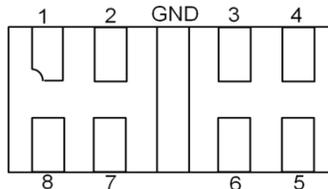
Features

- Clamping Voltage: 9V at 10A 100ns, TLP
9.4V at 5.5A 8μs/20μs
- IEC 61000-4-2 (ESD): Air — ±16kV, Contact — ±14kV
- IEC 61000-4-5 (Lightning): ±5.5A (8/20μs)
- 4 Channels of ESD Protection
- Low Channel Input Capacitance of 0.55pF Typical
- TLP Dynamic Resistance: 0.25Ω
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**

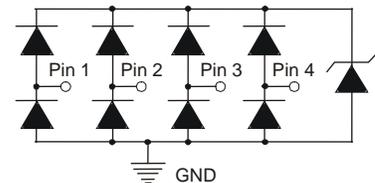
Mechanical Data

- Case: X2-DFN2010-8 (Type B)
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Schematic
- Terminals: Finish – NiPdAu, Solderable per MIL-STD-202, Method 208 **e4**
- Weight: 0.025 grams (Approximate)

Pin #	Description
1, 2, 3, 4	I/O
5, 6, 7, 8	No Connection



Pin Description (Bottom View)



Device Schematic

Ordering Information (Note 4)

Product	Compliance	Marking	Reel Size (inches)	Tape Width (mm)	Quantity per Reel
DT1240-04LP20-7	Standard	MU4	7	8	3,000/Tape & Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
 2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

Marking Information


MU4 = Product Type Marking Code
 YM = Date Code Marking
 Y = Year (ex: F = 2018)
 M = Month (ex: 9 = September)

Date Code Key

Year	2018	2019	2020	2021	2022	2023
Code	F	G	H	I	J	K

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	Conditions
Peak Pulse Current, per IEC 61000-4-5	I _{PP}	5.5	A	I/O to V _{SS} , 8/20μs
Peak Pulse Power, per IEC 61000-4-5	P _{PP}	60	W	I/O to V _{SS} , 8/20μs
ESD Protection – Contact Discharge, per IEC 61000-4-2	V _{ESD_CONTACT}	±14	kV	I/O to V _{SS}
ESD Protection – Air Discharge, per IEC 61000-4-2	V _{ESD_AIR}	±16	kV	I/O to V _{SS}
Operating Temperature	T _{OP}	-55 to +85	°C	—
Storage Temperature	T _{STG}	-55 to +150	°C	—

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation Typical (Note 5)	P _D	360	mW
Thermal Resistance, Junction to Ambient Typical (Note 5)	R _{θJA}	350	°C/W

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Conditions
Reverse Working Voltage	V _{RWM}	—	—	5.5	V	I _R =1mA, I/O to V _{SS}
Reverse Current	I _R	—	—	0.5	μA	V _R = 5V, I/O to V _{SS}
Reverse Breakdown Voltage	V _{BR}	6	—	—	V	I _R = 1mA, I/O to V _{SS}
Forward Clamping Voltage	V _F	-1.0	-0.85	—	V	I _F = -15mA, I/O to V _{SS}
Reverse Clamping Voltage (Note 6)	V _C	—	9.4	11	V	I _{PP} = 5.5A, I/O to V _{SS} , 8/20μs
ESD Clamping Voltage	V _{ESD}	—	9	—	V	TLP, 10A, t _p = 100 ns, I/O to V _{SS}
Dynamic Reverse Resistance	R _{DIF-R}	—	0.25	—	Ω	TLP, 10A, t _p = 100 ns, I/O to V _{SS}
Dynamic Forward Resistance	R _{DIF-F}	—	0.25	—	Ω	TLP, 10A, t _p = 100 ns, V _{SS} to I/O
Channel Input Capacitance	C _{I/O}	—	0.55	—	pF	V _{I/O} = 2.5V, V _{SS} = 0V, f = 1MHz

- Notes: 5. Device mounted on FR-4 PCB pad layout (2oz copper) as shown on Diodes Incorporated's suggested pad layout, which can be found on our website at <http://www.diodes.com/package-outlines.html>.
6. Clamping voltage value is based on an 8x20μs peak pulse current (I_{PP}) waveform.

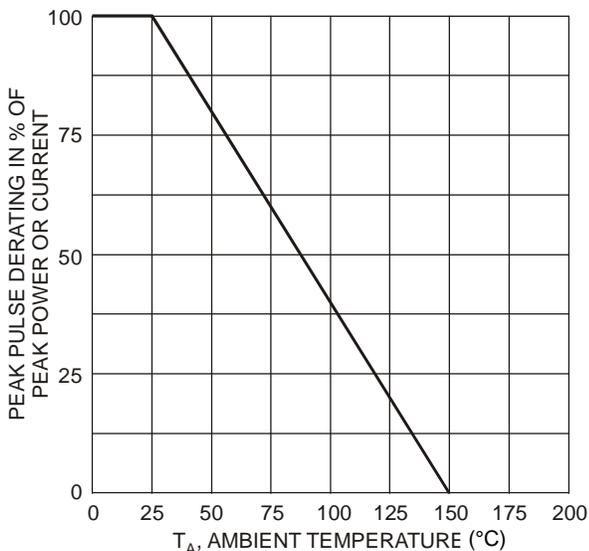


Figure 1 Pulse Derating Curve

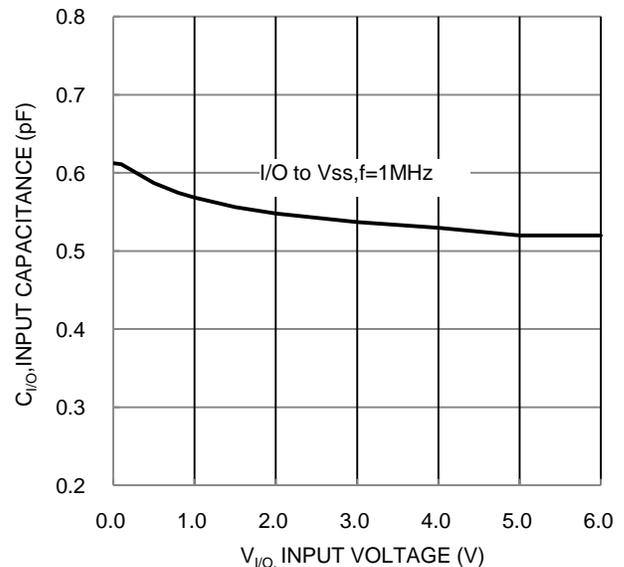


Figure 2 Input Capacitance vs. Input Voltage

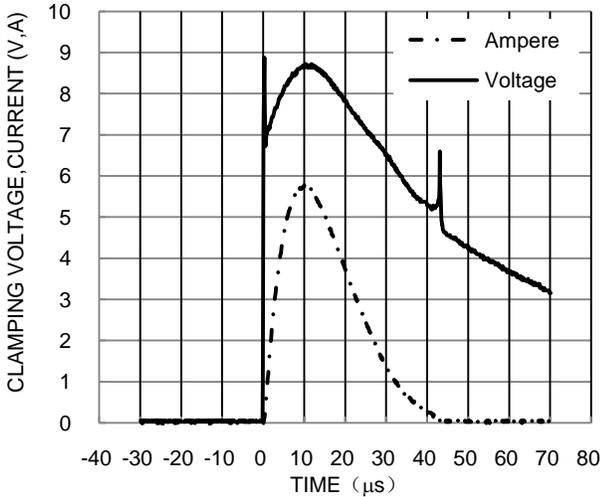


Figure 3. Waveform of Clamping Voltage, Current vs. Time (8/20µs, I/O to Vss)

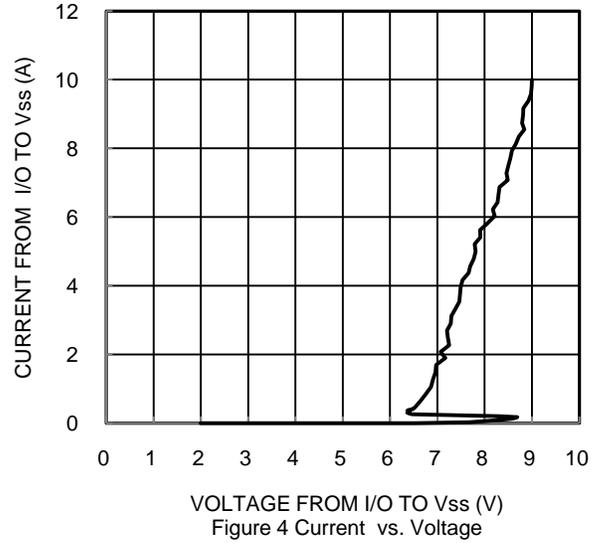
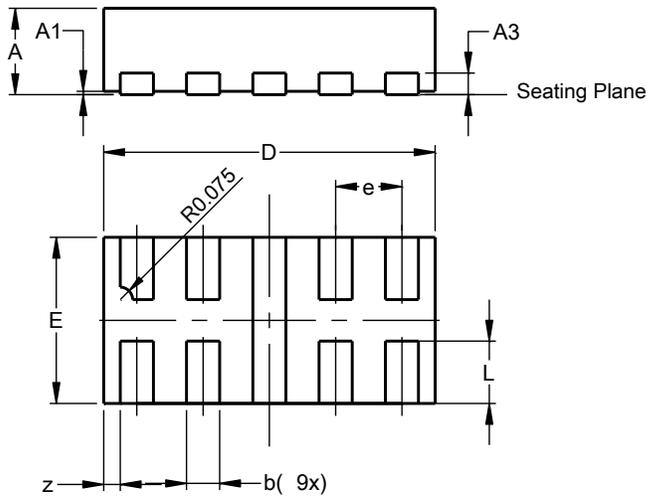


Figure 4 Current vs. Voltage

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

X2-DFN2010-8 (Type B)

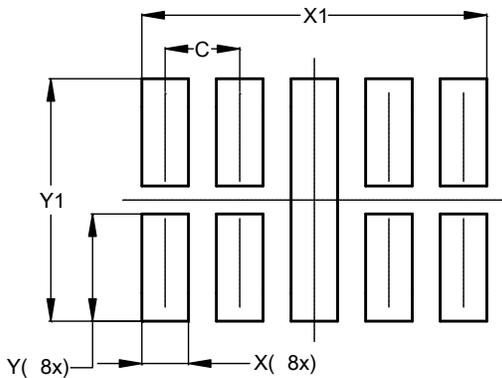


X2-DFN2010-8 (Type B)			
Dim	Min	Max	Typ
A	--	0.40	--
A1	0.00	0.05	0.02
A3	--	--	0.13
b	0.15	0.25	0.20
D	1.950	2.075	2.000
E	0.950	1.075	1.000
e	--	--	0.40
L	0.325	0.425	0.375
z	--	--	0.10
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

X2-DFN2010-8 (Type B)



Dimensions	Value (in mm)
C	0.400
X	0.250
X1	1.850
Y	0.575
Y1	1.300

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